

Claims

1. An imaging apparatus comprising:  
a semiconductor imaging device which converts incident light to an electrical signal;
- 5 an optical filter which is opposed to an incident surface of said semiconductor imaging device and transmits light of a certain wavelength; and  
a fixing member fixing said optical filter by means of adhesion using a filler-containing adhesive;
- 10 wherein a diameter of said filler is smaller than or equal to a pixel size of said semiconductor imaging device.
2. The imaging apparatus according to claim 1, wherein said fixing member is a three-dimensional substrate.
3. An imaging apparatus comprising:  
15 a semiconductor imaging device which converts incident light to an electrical signal; and  
a substrate fixing said semiconductor imaging device by means of adhesion using a filler-containing adhesive;  
wherein a diameter of said filler is smaller than or equal  
20 to a pixel size of said semiconductor imaging device.
4. The imaging apparatus according to claim 1 or 3, wherein said diameter of said filler is larger than or equal to 1/2 of a pixel size of said semiconductor imaging device.
5. The imaging apparatus according to claim 1 or 3, wherein  
25 said filler is spherical in shape.